

Listing of All Claims Including Current Amendments

1. (cancelled)
2. (cancelled)
3. (cancelled)
4. (currently amended) The image pick-up module of Claim [[1]] 24, wherein two legs of said V-shaped third section extend along a straight-line prolongation of said first and said second sections, respectively.
5. (cancelled)
6. (cancelled)
7. (withdrawn - currently amended) The image pick-up module of Claim [[1]] 24, wherein said at least one cable is bonded to an inner surface of the circuit board.
8. (currently amended) The image pick-up module of Claim [[1]] 24, wherein said at least one cable is bonded to an outer surface of said circuit board.
9. (cancelled).
10. (withdrawn - currently amended) The image pick-up module of Claim [[1]] 24, wherein said third section comprises at least one passage for said at least one cable leading away from said circuit board.
11. (withdrawn) The image pick-up module of Claim 10, wherein said at least one passage is configured as a marginal recess in said third section.
12. (withdrawn - currently amended) The image pick-up module of Claim [[1]] 24, wherein said third section comprises at least one passage for said at least one cable

leading away from said circuit board, wherein said at least one passage is configured as a substantially central opening in said third section.

13. (currently amended) The image pick-up module of Claim [[1]] 24, wherein ~~[[an]] the interior of said circuit board, defined by said first, second and third sections,~~ is filled with an electrically non-conductive filling compound.

14. (currently amended) The image pick-up module of Claim [[1]] 24, wherein said circuit board comprises a forth section arranged opposite said third section and accommodating said image sensor on its outer surface.

15. (currently amended) The image pick-up module of Claim [[13]] 14, wherein said forth section further comprises at least one of an electric component and at least one electric circuit-board conductor.

16. (cancelled)

17. (currently amended) The image pick-up module of Claim [[1]] 24, wherein said circuit board is provided on its outer surface with recesses for bonding of said image sensor.

18. (currently amended) The image pick-up module of Claim [[1]] 24, wherein said third section of said circuit board further comprises at least one contact for bonding said cable leading away from said circuit board.

19. (currently amended) The image pick-up module of Claim [[1]] 24, wherein said third section of said circuit board further comprises at least one electric circuit-board conductor for electrically connecting said first section and said second section.

20. (cancelled).

21. (currently amended) The image pick-up module of Claim [[1]] 24, wherein said first section and said second section of said board blank are flexibly connected via an additional section, but are arranged in spaced relationship at one and the same level, wherein said first section and said second section each serve for bonding said at least one cable, and wherein said third section is flexibly connected to said additional section on an end face of said additional section.

22. (cancelled)

23. (cancelled)

24. (previously presented) Image pick-up module, comprising:

an endoscope shaft having a longitudinal axis;

an electronic image sensor including an image pick-up surface transverse to the longitudinal axis of said shaft;

a circuit board electrically bonded to said image sensor, said circuit board comprising

first and second sections, said first and second sections each having a first end bonded to said image sensor and a second end, wherein said first and second sections extend longitudinally from said image sensor substantially perpendicular to the image pick-up surface of said sensor and substantially in parallel to one other; and

a third section having a substantially V-shaped configuration integrally formed with the second end of said second section;

at least one cable electrically bonded to said circuit board and leading away from said circuit board.

25. (cancelled)